



<b>Title of Change:</b>	WLP fab site change from Gunma, Japan to Niigata, Japan			
<b>Proposed first ship date:</b>	20 September 2016 (or earlier upon customer approval)			
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Hiroshi.Kojima@onsemi.com">Hiroshi.Kojima@onsemi.com</a>			
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Hiroshi.Kojima@onsemi.com">Hiroshi.Kojima@onsemi.com</a>			
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Satoru.Fujinuma@onsemi.com">Satoru.Fujinuma@onsemi.com</a>			
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.			
<b>Change Part Identification:</b>	Products manufactured at Niigata will be printed Date Code from <b>1627</b> on shipping MPN label.			
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____			
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____			
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s)			
<b>Description and Purpose:</b>				
To continuously supply products and increase our supply capacity to support increased demand, the Wafer Level Package (WLP) location will move from Gunma, Japan to Niigata, Japan. All equipment and most personnel were transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified.				
<b>Reliability Data Summary:</b>				
QV DEVICE NAME LV5216CS				
PACKAGE WLCSP36 2.97x2.97mm				
<b>Test</b>	<b>Specification</b>	<b>Condition</b>	<b>Interval</b>	<b>Results</b>
HTOL	JESD22-A108	Tjmax , 100 % max rated Vcc	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
TC	JESD22-A104	Ta= -40°C to +125°C	500 cyc	0/231
THB	JESD22-A101	85°C, 85% RH, bias	1008 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	-
<b>Electrical Characteristic Summary:</b> There is no change in the electrical performance. Datasheet specifications remain unchanged.				
<b>List of affected Standard Parts:</b>				
<b>Part Number</b>		<b>Qualification Vehicle</b>		
LV5216CS-TE-L-E		LV5216CS-TE-L-E		